ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH PAD CONNECTION AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: forming a peripheral lead having a peripheral lead bottom side, a peripheral lead top side, a peripheral lead non-horizontal side, a peripheral lead horizontal ridge, and a peripheral lead conductive plate, the peripheral lead horizontal ridge protruding from the peripheral lead non-horizontal side; forming a first top distribution layer on the peripheral lead top side, the first top distribution layer having a first top terminal; connecting an integrated circuit to the first top distribution layer, the integrated circuit having a central portion directly over a plurality of the first top terminal; and applying an insulation layer directly on a bottom extent of the first top distribution layer and a peripheral lead ridge lower side of the peripheral lead horizontal ridge.

(Fig. 1)